

J Std 003c

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'IPC Standards Committee Reports Assembly amp Joining

July 13th, 2018 - This task group met a second day to resolve comments on criteria common to both IPC J STD 001 and Task Group completed work on IPC J STD 003C"IPC J STD 033C CN ??

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July 1st, 2018 - Document Number J STD 003C Revision Level RENUMBERED Status Current Publication Date Oct 1 2013 Page Count 27 pages'

'IPC J STD 003B necompany ru

June 30th, 2018 - Title IPC J STD 003B Author 850 romanova Created Date 1 20 2009 11 40 18 AM'

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'IPC EIA J STD 003 Solderability Tests for Printed Boards

July 12th, 2018 - Document Number IPC J STD 003C WAM1 amp 2 Revision Level REVISION C AM 2 Status Current Publication Date Oct 2 2017 Page Count 48 pages'

'J STD 003 Solderability Tests for Printed Boards

July 8th, 2018 - J STD 003 Revision C September 2013 Complete Document Solderability Tests for Printed Boards Includes all amendments and changes through Amendment 2 September'

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June 24th, 2018 - BackAmendment 1 to the J STD 003C corrects editorial errors as well as adds clarifying statements to many areas of the document Released May 2014'

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